

ABSTRACT OF THE DISCLOSURE

Provided is an envelope which includes: a first substrate; a second substrate opposed to the first substrate; a frame interposed between the first
5 substrate and the second substrate; and a low melting point metal for bonding the first substrate and the frame to each other. In particular, in such a configuration, the substrate or the frame has a first region and a second region which are brought into
10 contact with the low melting point metal, and in the first region, a material capable of higher maintaining airtightness with the low melting point metal than the second region is in contact with the low melting point metal, while in the second region,
15 a material having a stronger binding power on the low melting point metal than the first region is in contact with the low melting point metal.